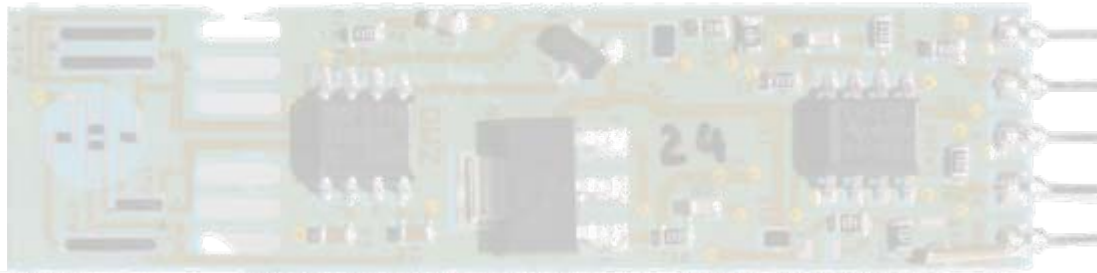


SMD pressure and flow sensor for compressed air in LTCC technology with integrated electronics

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Flow Sensors session - Sept 9th, 10:30-12:00



Laboratoire de Production Microtechnique

<http://lpm.epfl.ch/tf>

Ecole Polytechnique Fédérale de Lausanne (EPFL)

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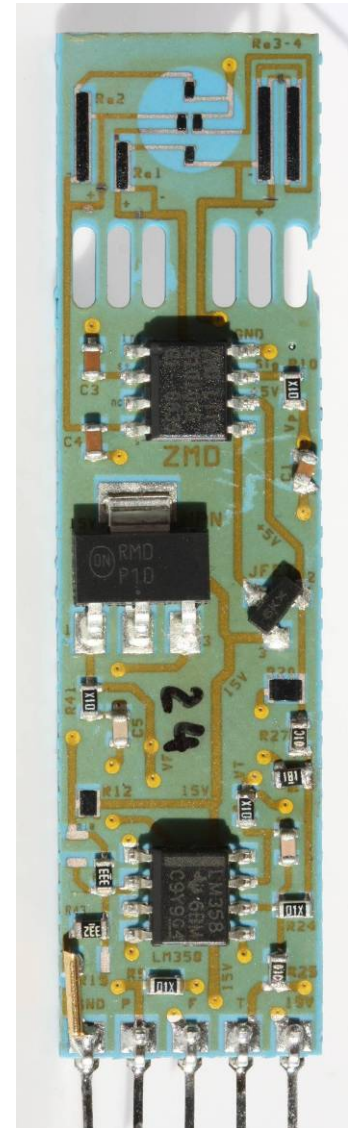
What is it all about?

An integrated sensor:

- ...in **LTCC**, for the pneumatic industry
- ...**SMD** mountable by soldering
- ...with **integrated electronics**

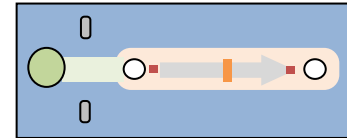
For measuring:

- **air pressure** 0...6 bar
- **air flow** 0...100 NL/min
- **air temperature** 0...100 °C



Presentation outline

1. Introduction – the needs of the industry
2. Integrated sensor – manufacturing
3. Measurements – pressure, flow, temp.
4. Conclusions & outlook



1. Motivations

Precise fluid measurement (p , flow, T): OK

- numerous methods already exist
- usually with specific CMOS chips

Still an issue for industrial devices:

- coarse measurements for diagnostics

safe & reliable

low-cost

easy to integrate → “total” SMD

1. Motivations

Focussing on custom pneumatic circuits:

- actuator feedback: *has the piston moved?*
- monitoring: *what is the valve output pressure?*
- circuit diagnostics: *is the channel clogged / leaking?*

⇒ **Measurement of pressure, flow, and temperature**

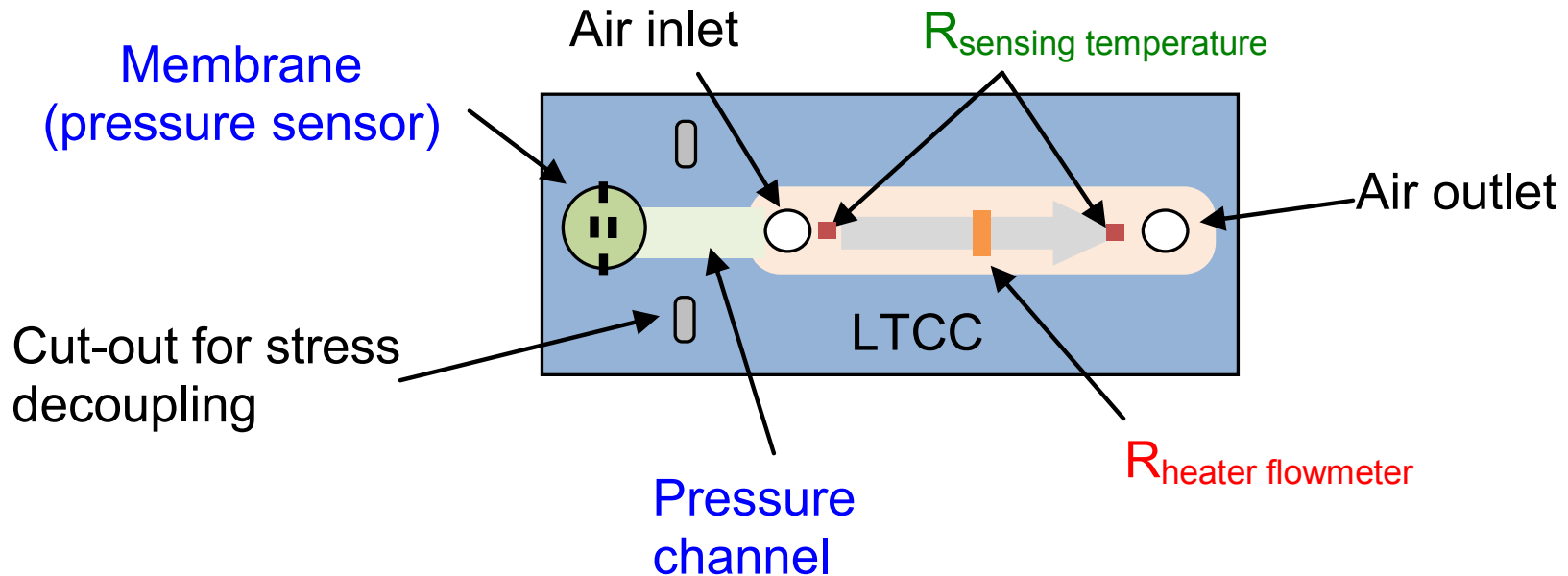
Sensors requirements:

- simple, cheap, robust, reliable
- **no need for precision**
- easily mountable (SMD for both electronics + fluidics)
- integrated electronics (no need for signal processing)

2. Integrated sensor

Proposal: an LTCC integrated sensor with electronics

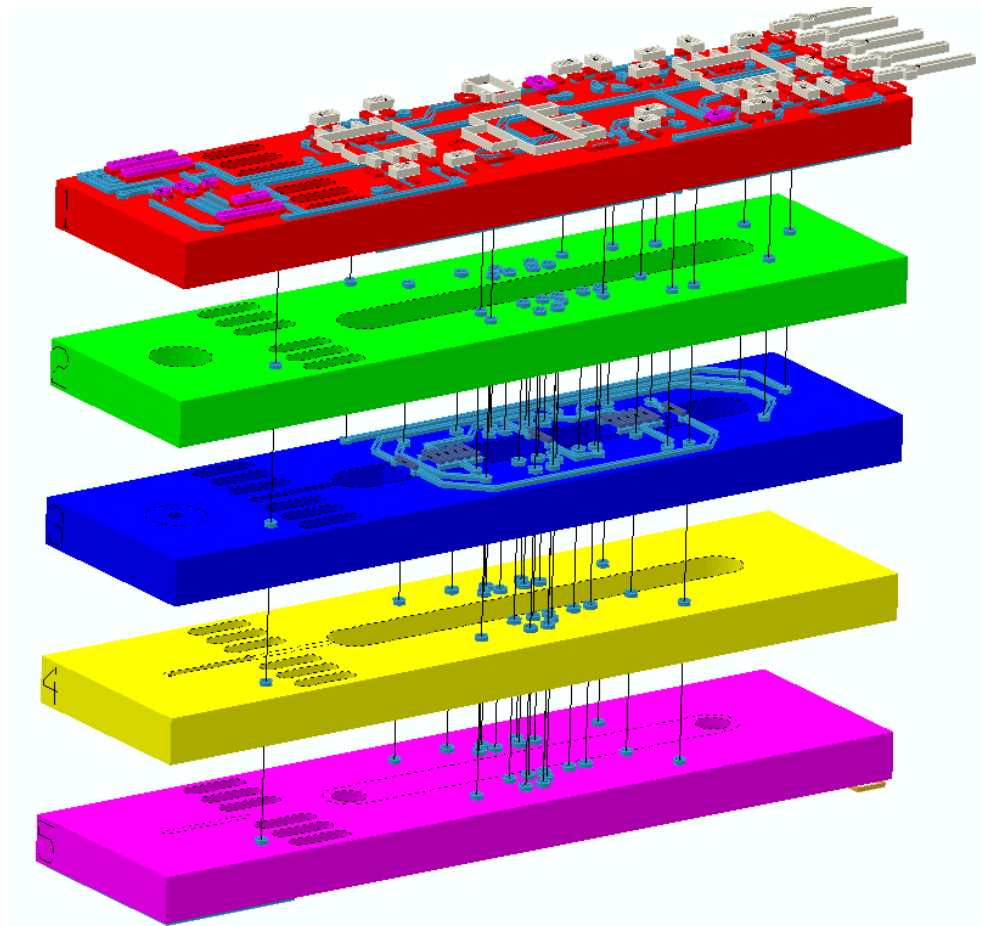
- pressure
- flow
- temperature



2. Screen-printing, stacking

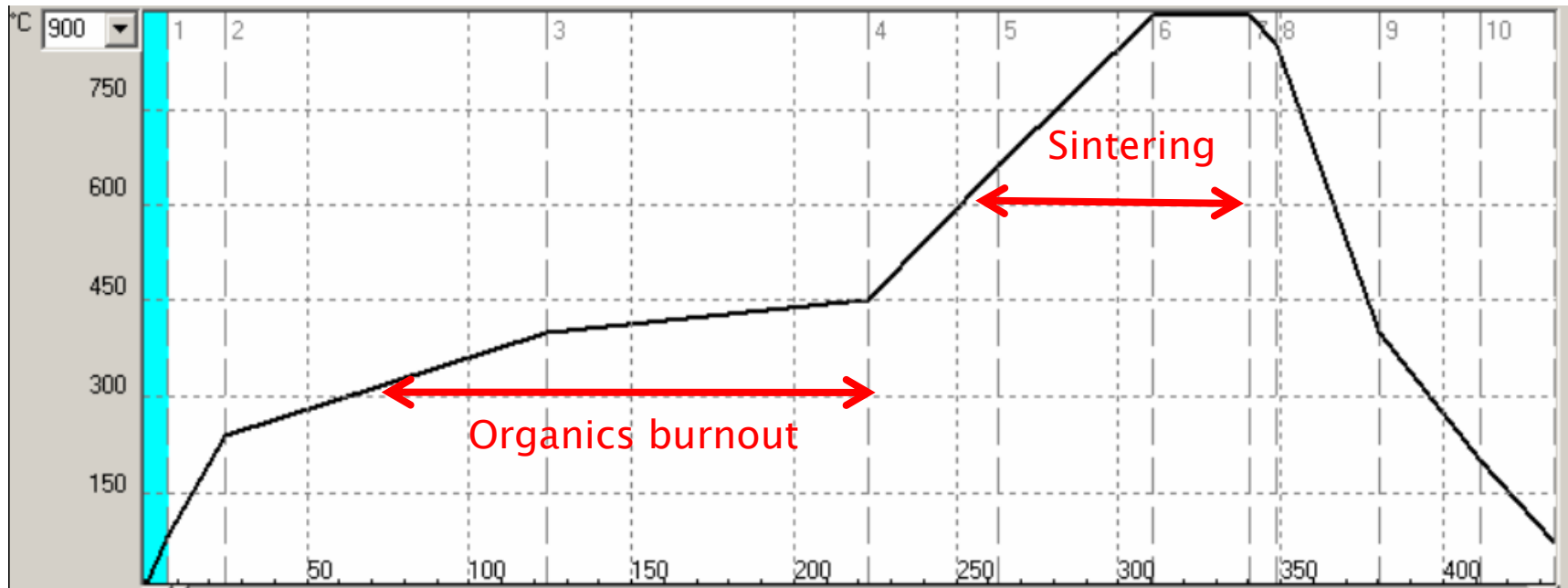
LTCC DuPont 951

- **Vias**
Ag *DuPont 6141*
- **Conductor tracks**
Ag:Pd *DuPont 6146*
Ag *DuPont 6145*
- **Resistors**
10 k Ω /□ *DuPont 2041*
PTC *DuPont 5092D*

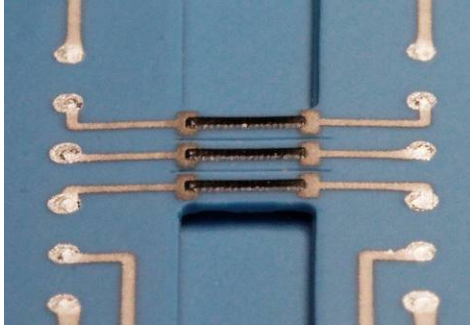


2. Lamination and firing

- Successive partial and total laminations:
 - **constrained rubber @ 90 bar, 46°C**, 10 min
 - **metal plates @ 80 bar, 25°C**, 10 min
- Firing in air, 875°C, heating ramp 5 K/min

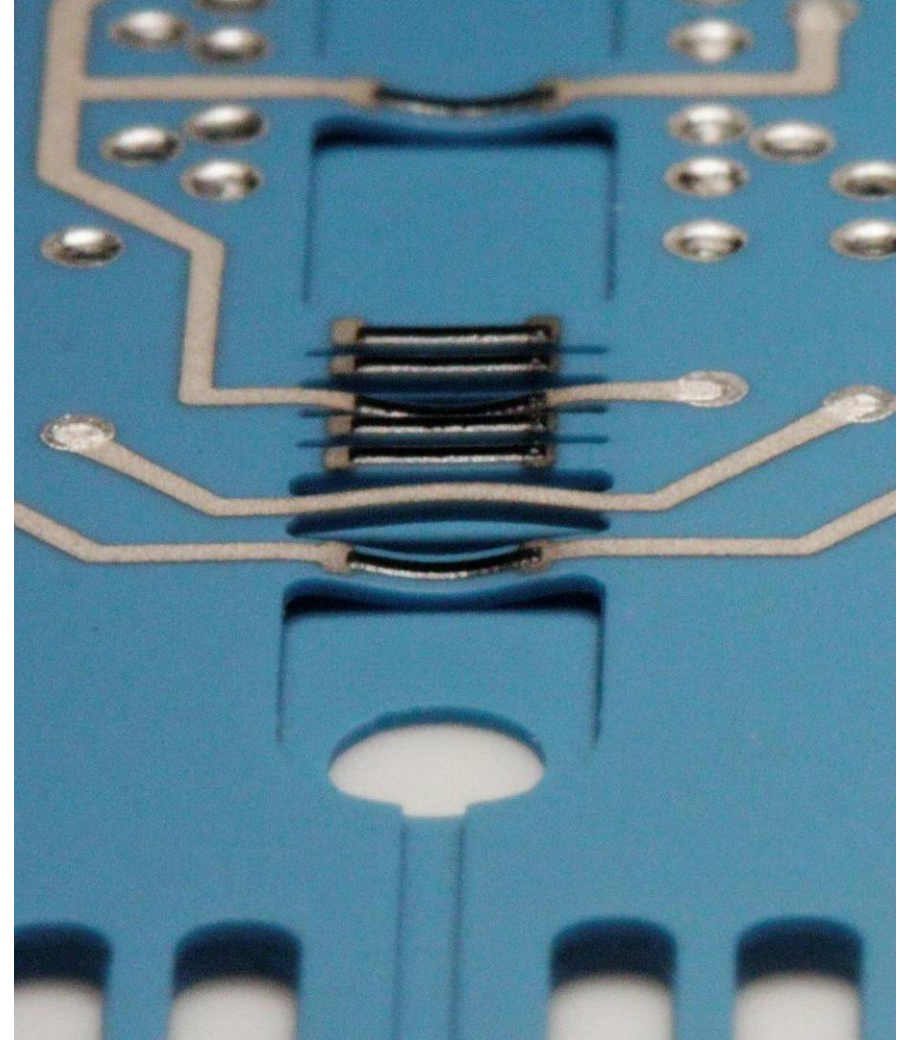


2. Manufacturing issues



Differential sintering issues
between LTCC and pastes
→ **deformations**

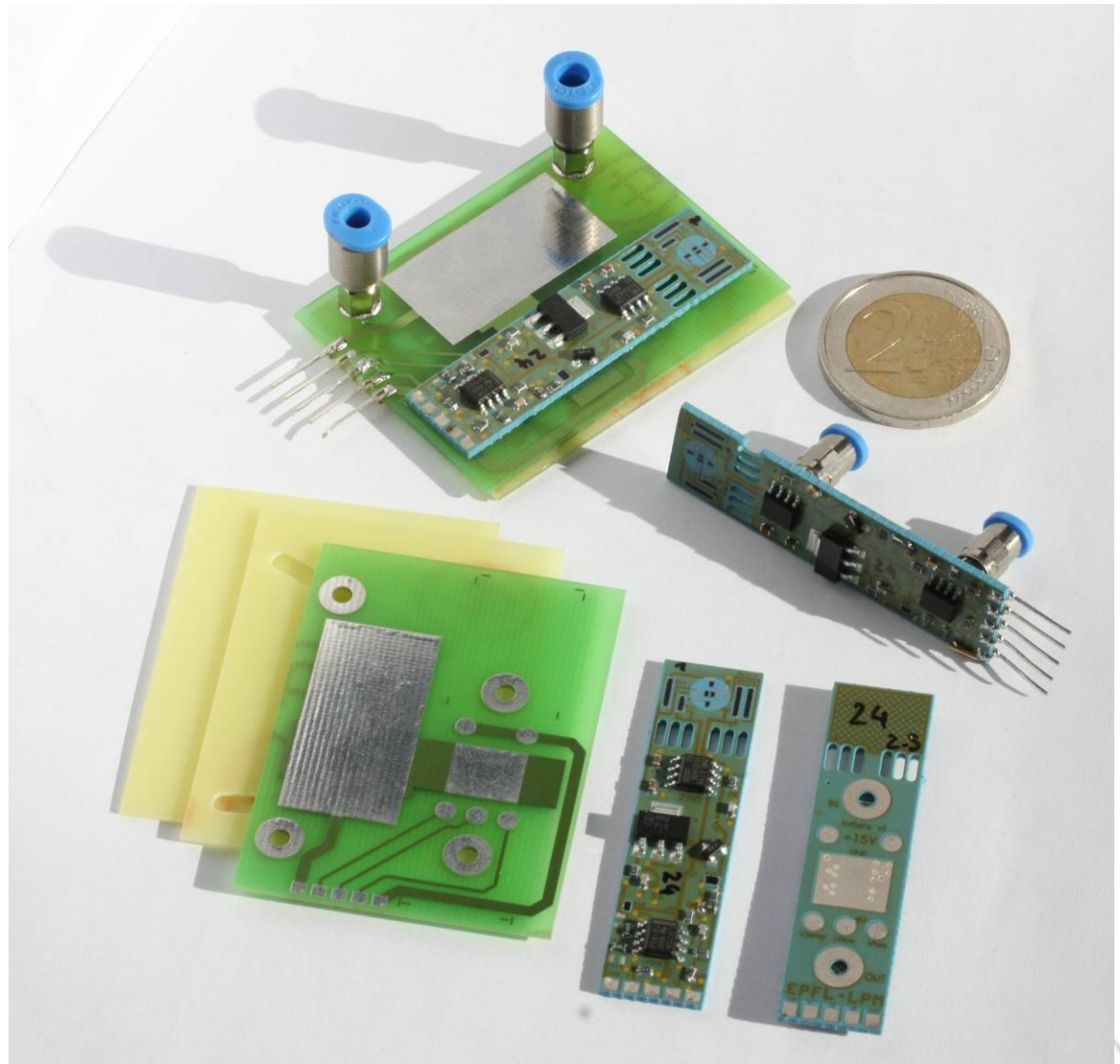
⇒ Need adapted layout or
sacrificial layers



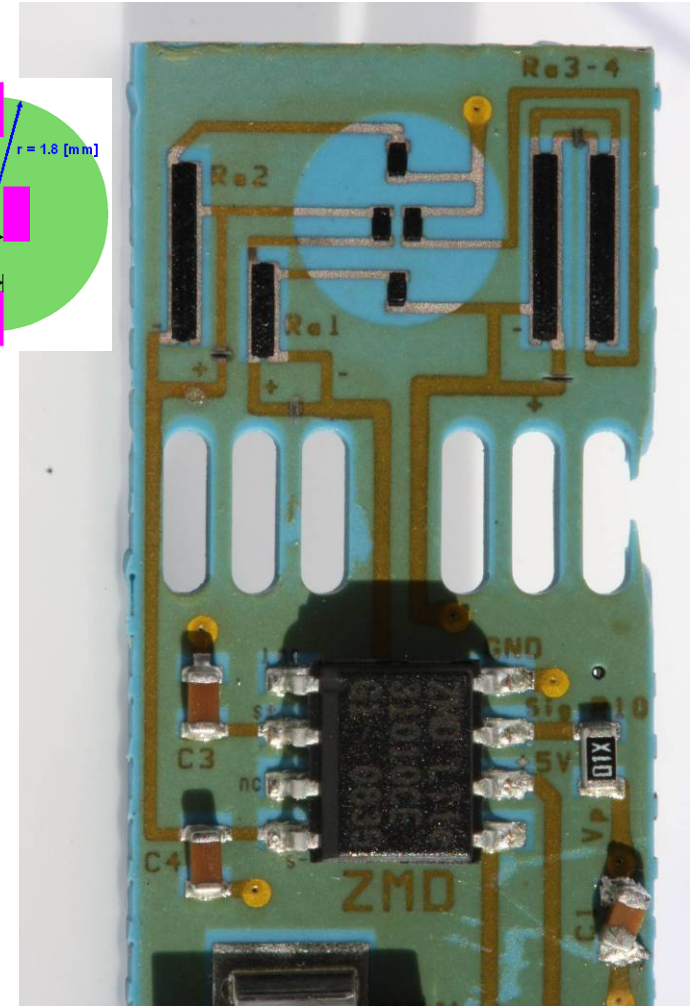
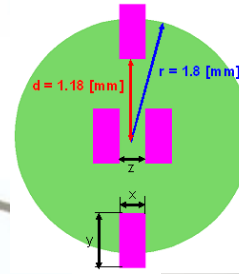
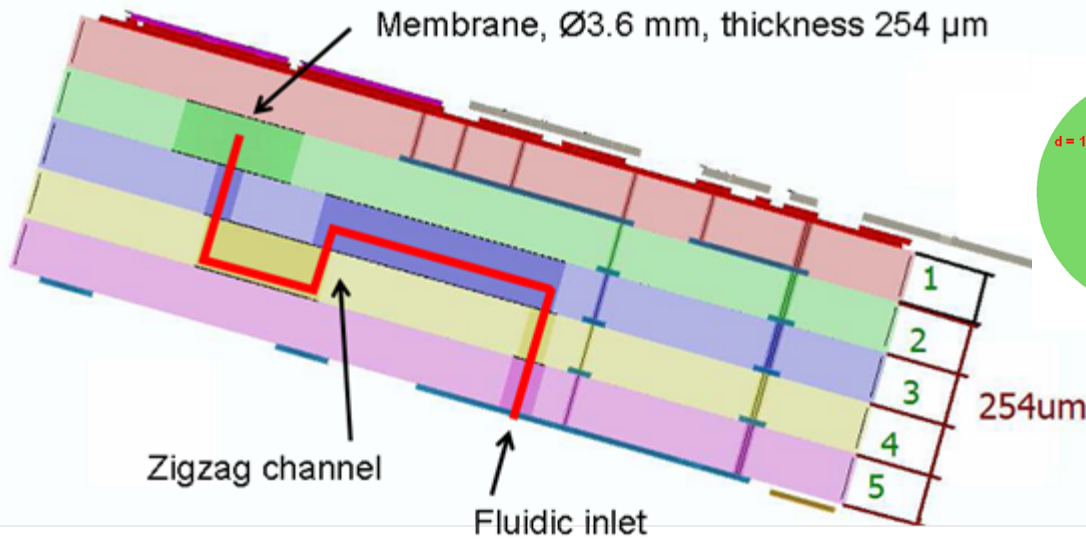
2. Assembly on test PCB

Test PCB

- Fluidic connections
- Electrical interconnects
- Large copper planes for future thermal studies



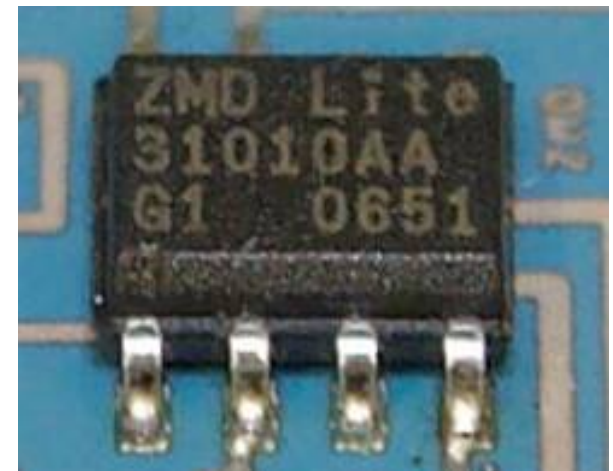
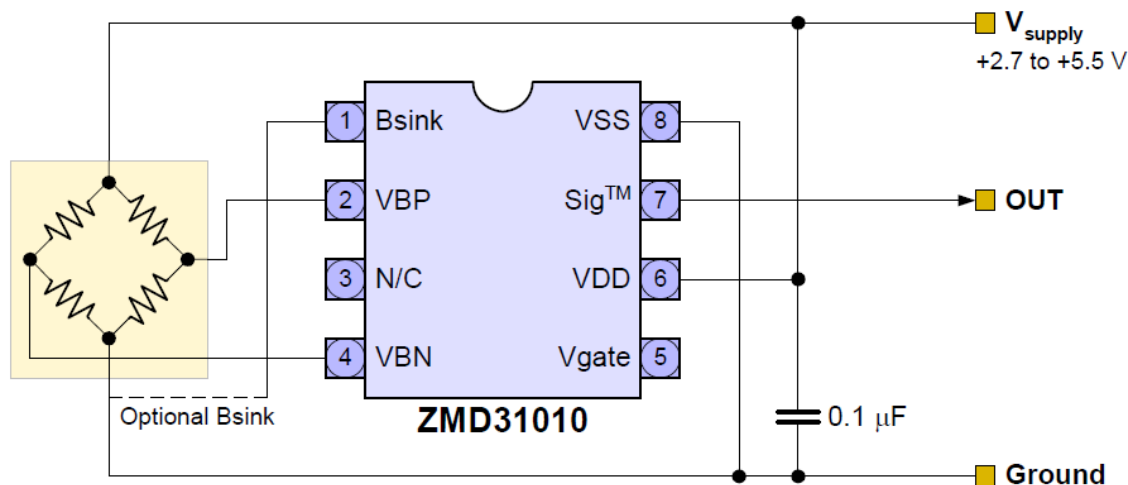
3. Pressure sensor



- Nominal pressure: **6 bar**
- **Piezoresistive bridge** on circular membrane
- Pressure path to avoid stress concentration on membrane

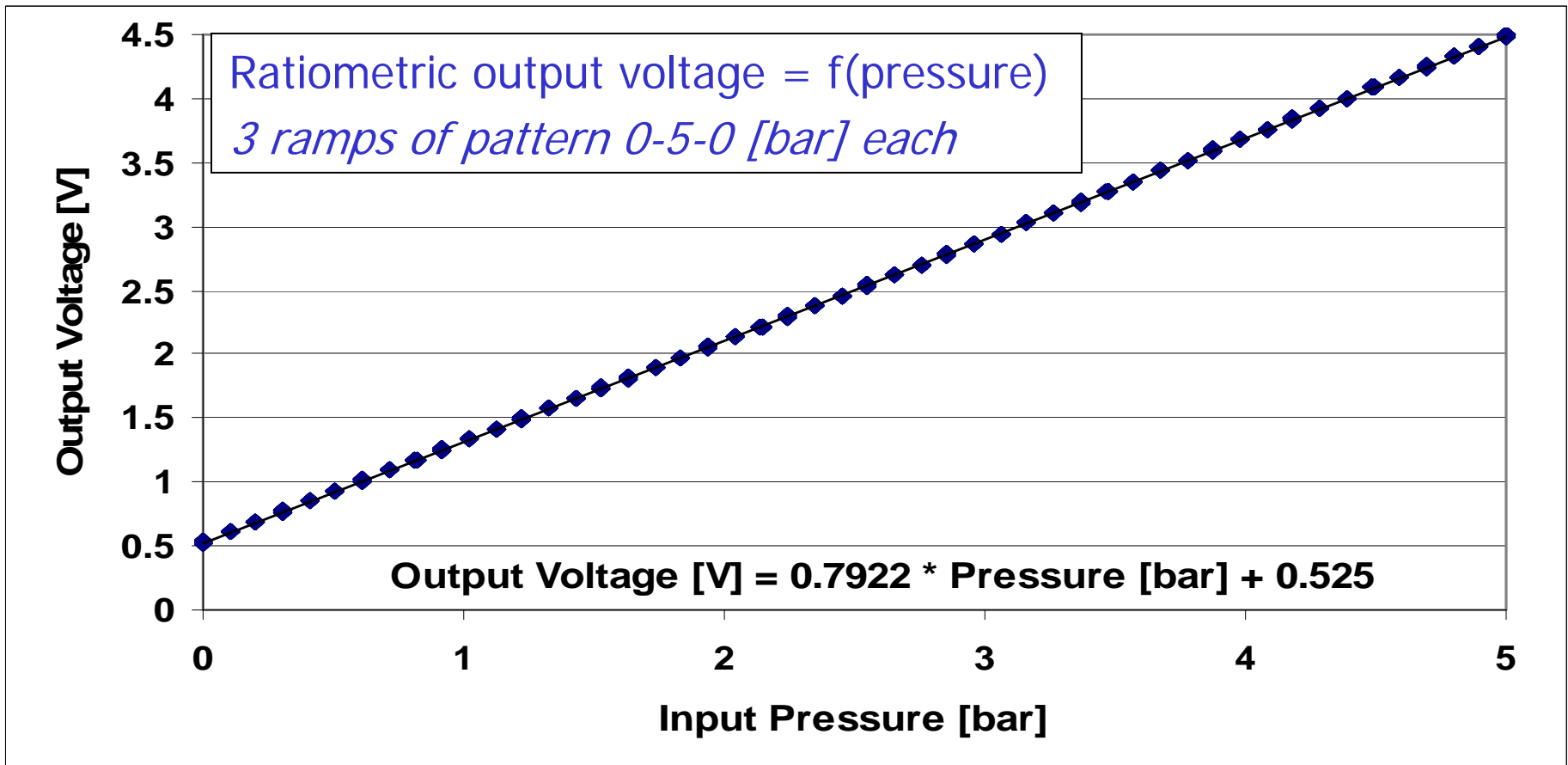
3. Pressure signal conditioning

- Easy adjustment of gain/offset
 - ⇒ Wheatstone bridge
 - ⇒ **programmable integrated conditioner** (*ZMD 31010*)



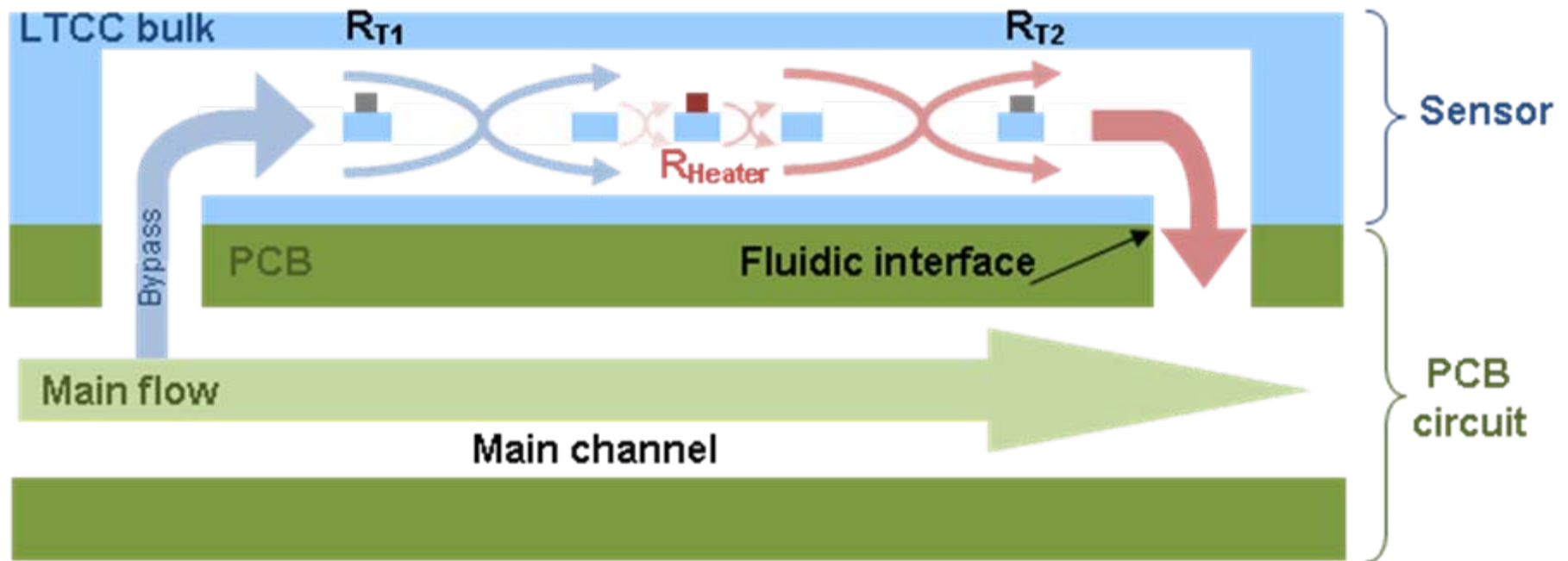
3. Performance (pressure)

- Very good repeatability: <0.1% (former prototype)
- Precision = f (voltage reference) (~1-2 %)

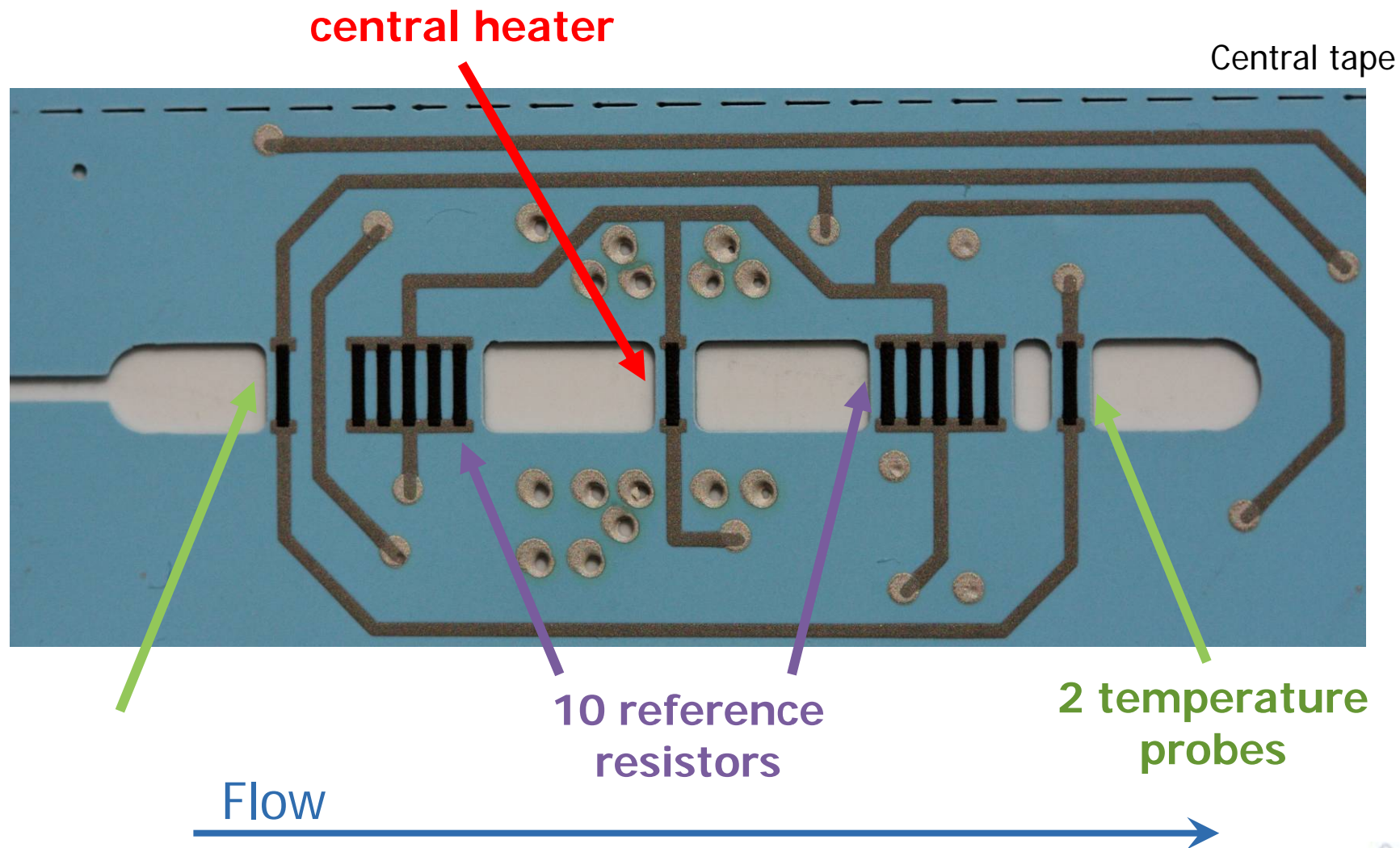


3. Flow sensor

- Flow range: 0...20 NL/min (100 NL/min with bypass)
- Reaction time: <3 s
- Measuring principle: **anemometric, 1 central heater**

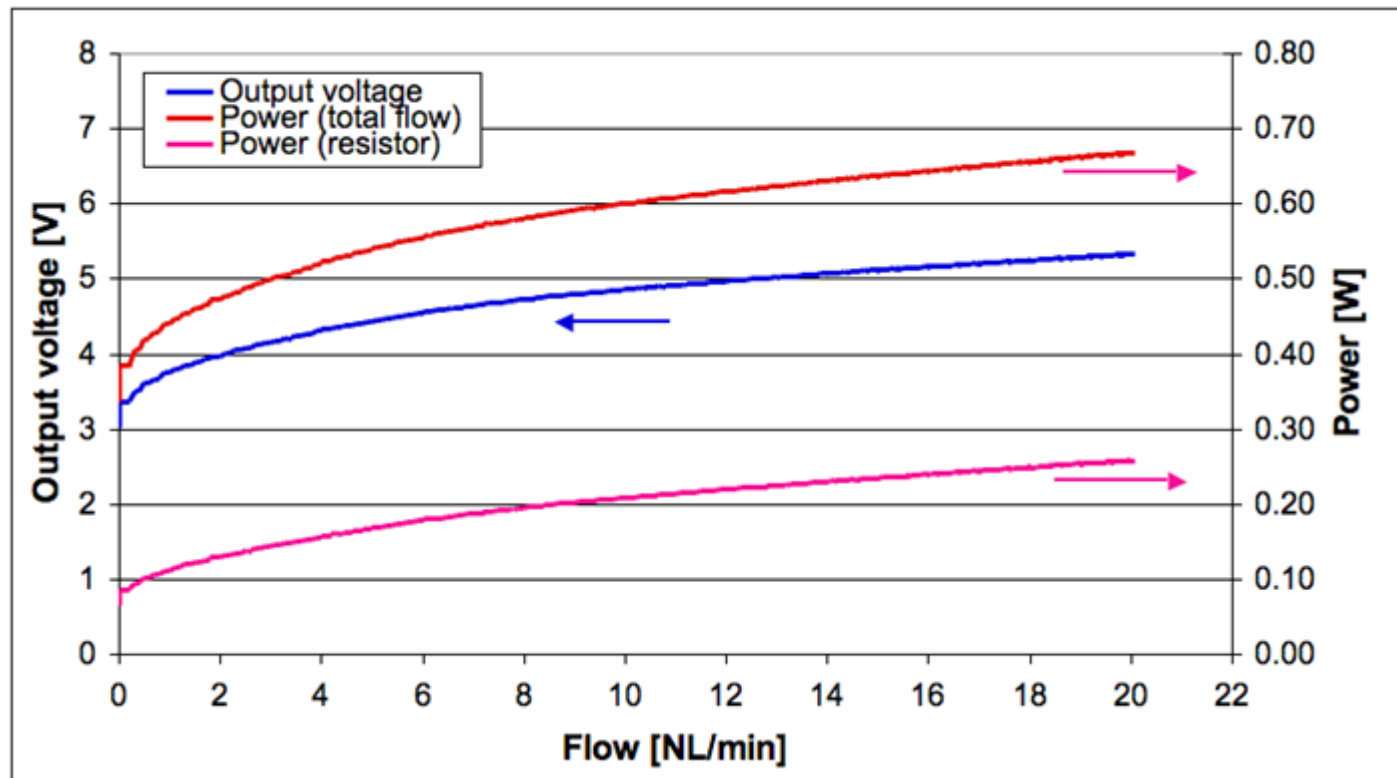


3. Resistors layout



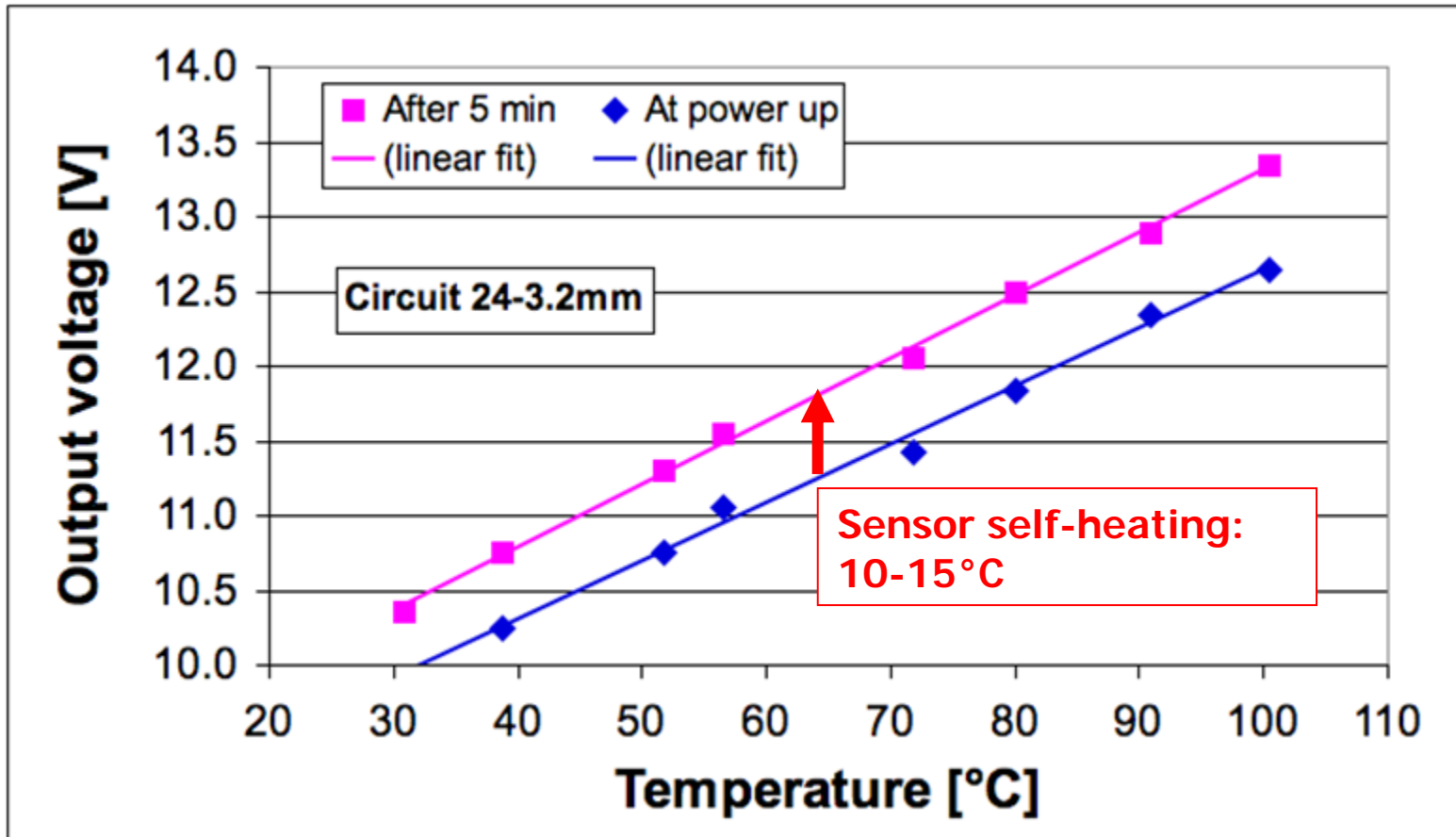
3. Performance (flow)

- Output voltage in function of flow (here w/o bypass)
- Output well correlated with dissipated power (square root with offset)
- High total dissipation due to linear regulation → **go to switching**



3. Temperature sensor

- Two PTC thermistors placed in channel near orifices

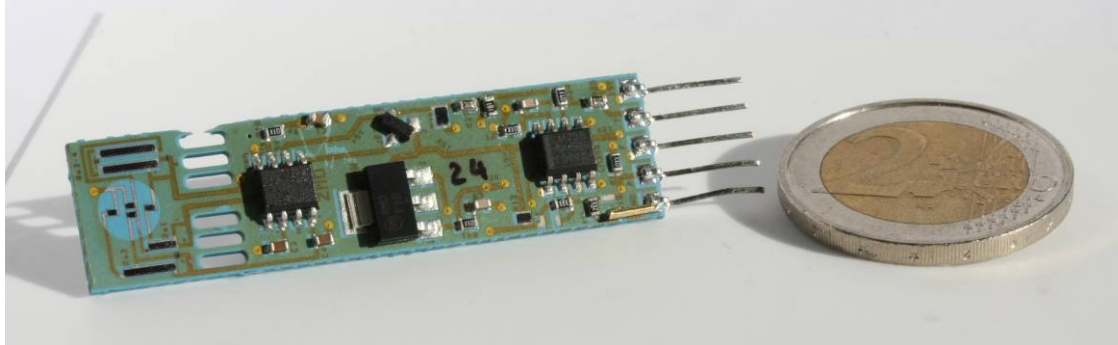


Measured under 12 V in air oven

Idle sensor current: ~32 mA

4. Conclusions & outlook

- Simple & cheap LTCC compressed air diagnostics sensor
- Assembly by SMD
- Pressure: 0...6 bar, piezoresistive
- Flow: 0...20 NL/min (higher with bypass), anemometric, constant temp.
- Temperature: 0...100°C coarse measurement



- Thermal characterisation + optimisation
- Go to switching regulator for heater

The end – questions?



*Thank you for your attention...
...and enjoy Switzerland!*

**Feel free to contact us for a lab visit here at EPFL:
LPM (Laboratoire de Production Microtechnique)
in the BM (Bâtiment de Microtechnique)**

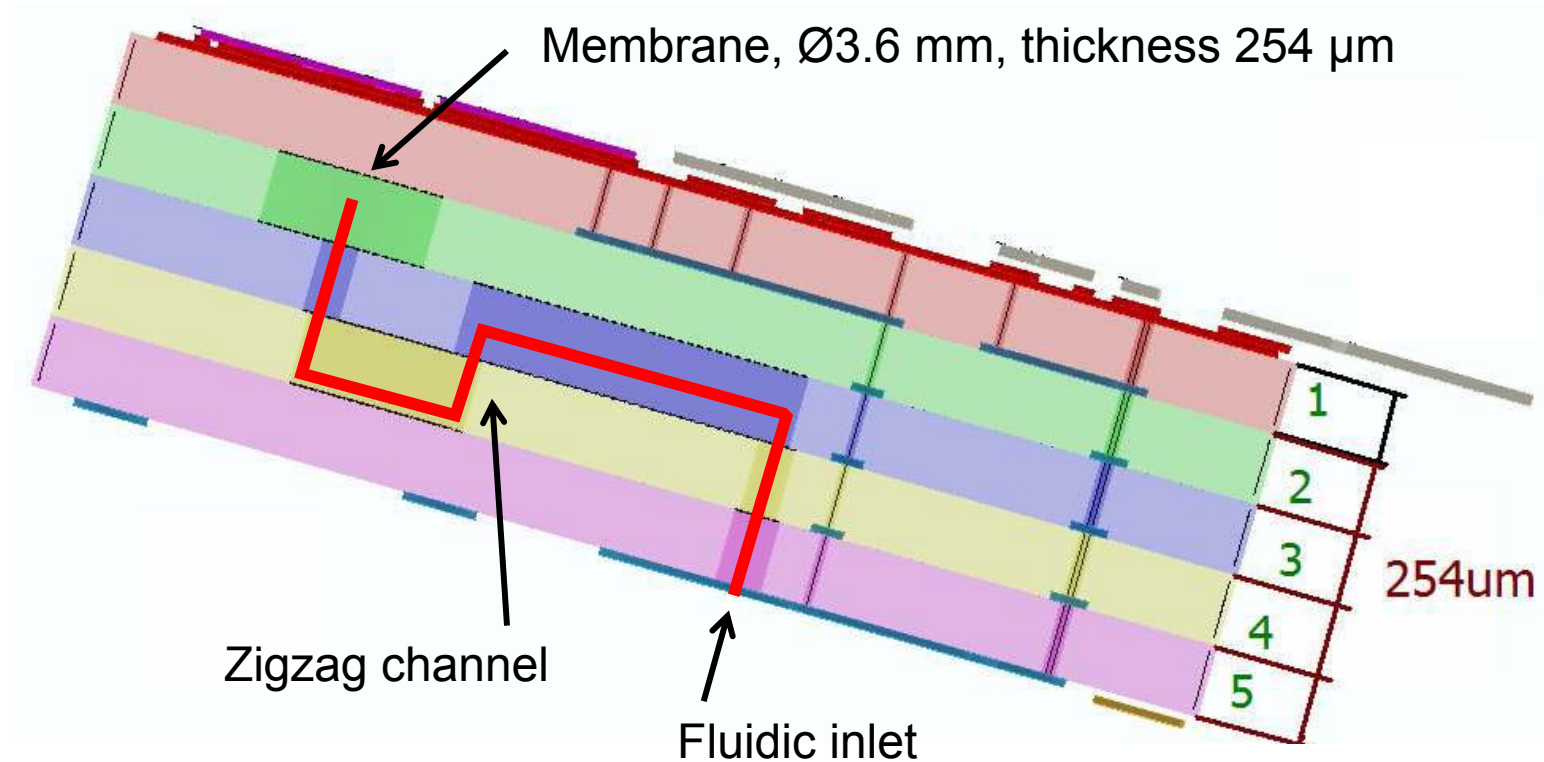
Supplementary slides

2. Specs

- Hybrid design: thick-film + SMD devices
- Assembly and connections by flip-chip
⇒ use of **different solder pastes**:
 - for electronics: lead-free Sn96.5-Ag3.0-Cu0.5, 220°C
 - for the whole sensor on PCB: SnBi, 138°C
- 5 pins: ground, signals (p, F, T) and power +15V

2. Pressure fluidics

- 200- μm membrane decoupled from fluidic inlet (reduction of assembly stress influence)
- Channel in zigzag (issues with long channels)



3. Flow vs pressure

Pressure in channel increasing with flow

